

IN THE CLAIMS:

1-9 (Canceled)

10. (Previously Presented) A method of providing on a semiconductor wafer at least one region carrying information for identification, comprising:
providing a semiconductor wafer; and
providing the at least one region with magnetic means, wherein the magnetic means are provided by ion implantation of magnetic ions.

11-31 (Canceled)

32. (Currently Amended) The ~~semiconductor wafer~~ method according to ~~claim 2~~ claim 10, wherein the magnetic means are proximate a semiconductor wafer edge.

33. (Currently Amended) The ~~semiconductor wafer~~ method according to ~~claim 2~~ claim 10, wherein the magnetic means are proximate an inner region of a semiconductor wafer surface, where a vacuum chuck apparatus having magnetic reading capabilities may engage the semiconductor wafer.

34-36 (Canceled)

37. (Previously Presented) The method according to claim 10, further comprising covering the magnetic means with at least one film layer.